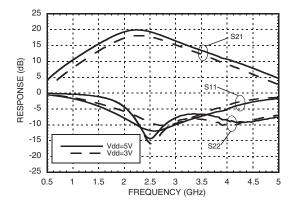


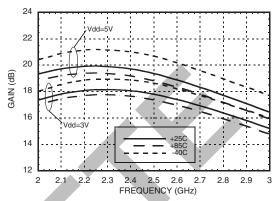


GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

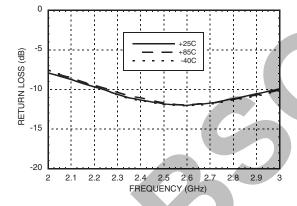
Broadband Gain & Return Loss



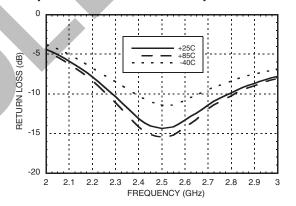
Gain vs. Temperature



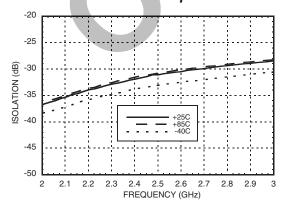
Input Return Loss vs. Temperature [1]



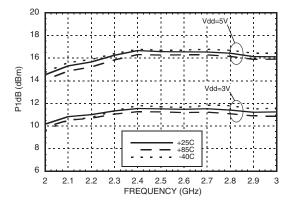
Output Return Loss vs. Temperature [1]



Reverse Isolation vs. Temperature [1]



P1dB vs. Temperature



[1] Vdd = 5V

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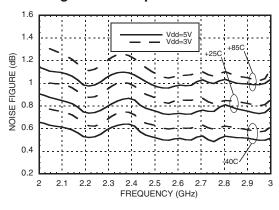
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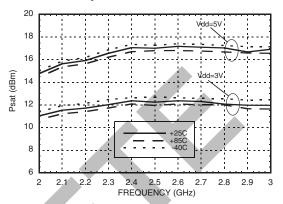


GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

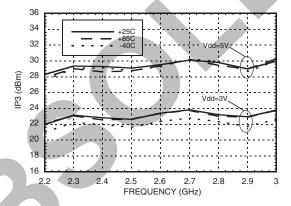
Noise Figure vs. Temperature [1]



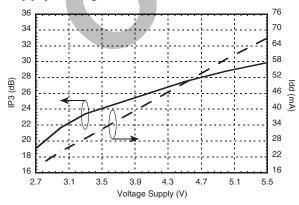
Psat vs. Temperature



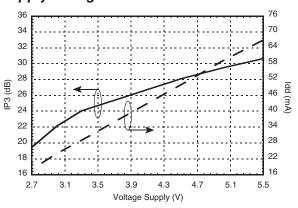
Output IP3 vs. Temperature



Output IP3 and Idd vs. Supply Voltage @ 2300 MHz



Output IP3 and Idd vs. Supply Voltage @ 2500 MHz



[1] Measurement reference plane shown on evaluation PCB drawing.

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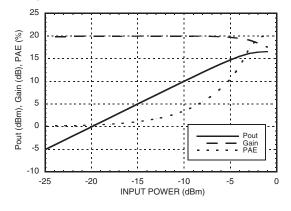
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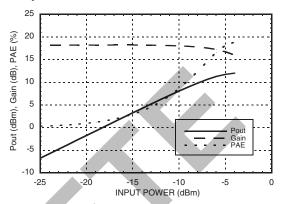


GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

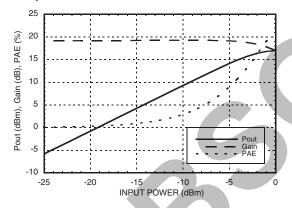
Output Power, Gain & PAE @ 2300 MHz [1]



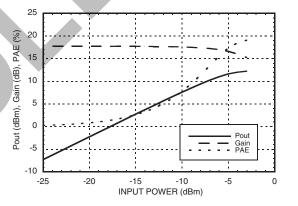
Output Power, Gain & PAE @ 2300 MHz [2]



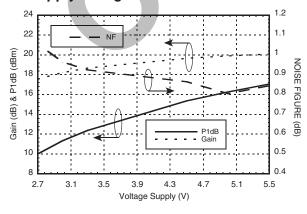
Output Power, Gain & PAE @ 2500 MHz [1]



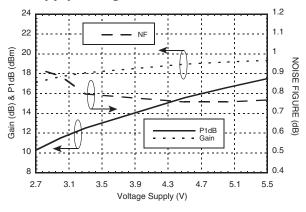
Output Power, Gain & PAE @ 2500 MHz [2]



P1dB, Gain, & Noise Figure vs. Supply Voltage @ 2300 MHz



P1dB, Gain, & Noise Figure vs. Supply Voltage @ 2500 MHz



[1] Vdd = 5V [2] Vdd = 3V

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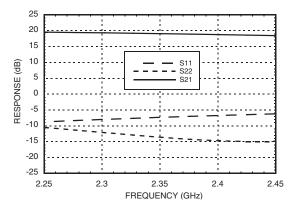
HMC667LP2 / 667LP2E

v02.1110

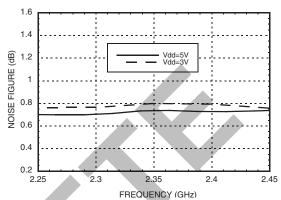


GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

Gain & Return Loss w/ SDARS Tune [1]



Noise Figure vs. Vdd w/ SDARS Tune [2]



Absolute Maximum Ratings

Drain Bias Voltage (Vdd)	+6 Vdc	
RF Input Power (RFIN)	+10 dBm	
Channel Temperature	150 °C	
Continuous Pdiss (T= 85 °C) (derate 5.88 mW/°C above 85 °C)	0.38 W	
Thermal Resistance (Channel to Ground Paddle)	170 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	



[1] Vdd = 5V [2] Measurement reference plane shown on evaluation PCB drawing.

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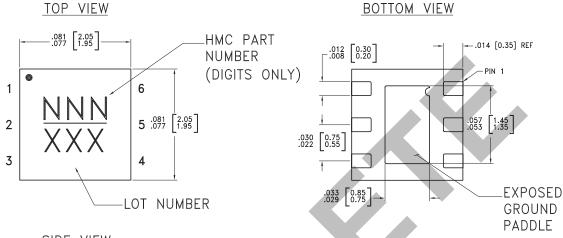
HMC667LP2 / 667LP2E

v02.1110

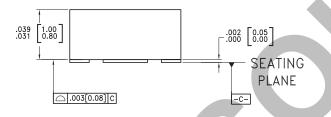


GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

Outline Drawing



SIDE VIEW



NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED $0.05 \mathrm{mm}$.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC667LP2	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	667 XXX
HMC667LP2E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>667</u> XXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 3-Digit lot number XXX





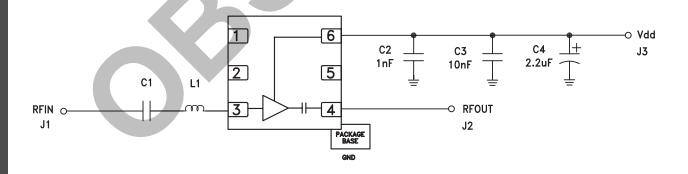
GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 2, 5	GND	These pins and package bottom must be connected to RF/DC ground.	GND =
3	RFIN	This pin is DC coupled See the application circuit for off-chip components	RFINO ESD
4	RFOUT	This pin is AC coupled and matched to 50 Ohms.	RFOUT ESD =
6	Vdd	Power supply voltage. Bypass capacitors are required. See application circuit.	Vdd O ESD

Components for Selected Band

Components	C1	L1	Evaluation PCB Number
Broadband	2.7 pF	2.0 nH	121891
SDARS	2.2 pF	4.3 nH	122404

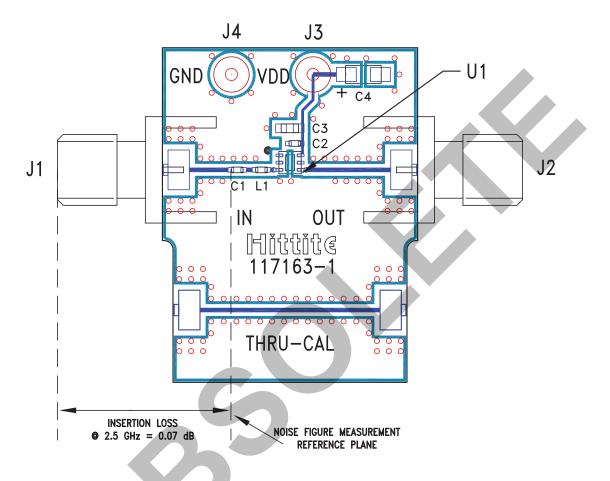






GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 2.3 - 2.7 GHz

Evaluation PCB



List of Materials for Evaluation PCB [1]

Item	Description	
J1 - J2	PCB Mount SMA Connector	
J3 - J4	DC Pin	
C1	2.7 pF Capacitor, 0402 Pkg.	
C2	1000 pF Capacitor, 0402 Pkg.	
C3	10 nF Capacitor, 0603 Pkg.	
C4	2.2 µF Capacitor, CASE-A Tantalum	
L1	2 nH Inductor, 0402 Pkg.	
U1	HMC667LP2(E) Amplifier	
PCB [2]	117163 Evaluation PCB	

^[1] When requesting an evaluation board, please reference the appropriate evaluation PCB number listed in the table "Components for Selected Band" on previous page

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350